**LaserCleave™ - SSP**

The LaserCleave™ range from world leading laser processing tool supplier and creator of the original LaserCleave™ process for optical fiber termination.

The LaserCleave™ SSP, Provides the optimum pre-polish cleave of fiber and epoxy for **Single Step Polishing** of simplex optical interconnect termination. OpTek’s proprietary LaserCleave™ process cuts close to the ferrule end face eliminating all but one polish step with a finishing film, saving on materials, time and equipment while improving your first pass yield.

### System Performance

- **Process speed:** Typically >500UPH
- **Small protrusion:** Typically <30µm(LC) <35µm(SC)
- **Single step polish:** Eliminate unnecessary polishing.
- **Polish friendly shape:** Rounded end, no sharp corner or edges.
- **Enhanced features:** Smooth finish, non-contact process.
- **Reliable:** No core cracks or cleaving back into ferrule.
- **Flexibility:** Interchangeable port for different connectors.
- **Ergonomic:** User friendly design and operation.

### System Requirements

- **Power:** Single phase, 1.7kVA
- **Cooling:** Air cooled: Water cooling option
- **Vision:** Integrated vision systems
- **Shards:** Large capacity collection >1M fiber shards
- **Size:** Bench top (W756xD505xH245mm)
- **Weight:** 35kg (bench top model)